



0,80mm PITCH BASIC BTE, BSE SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTE or www.samtec.com?BSE

Insulator Material:
Liquid Crystal Polymer

Contact Material:
Phosphor Bronze



Plating:
Au over 50µ" (1,27µm) Ni

Current Rating:
2A @ 80°C ambient

with 5mm Stack Height

Operating Temp Range:
-55°C to +125°C

Voltage Rating:
225 VAC with 5mm

Stack Height

Max Cycles: 100

RoHS Compliant: Yes

Processing:

Max Processing Temp:
230°C for 60 seconds, or

260°C for 20 seconds 3x

Lead-Free Solderable: Yes

SMT Lead Coplanarity:
(0,10mm) .004" max (020-080)

(0,15mm) .006" max (100-120)

Board Stacking:

For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

BTE	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	A	OTHER OPTION
	-020, -040, -060, -080, -100, -120	Specify LEAD STYLE from chart.	-L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail -F = Gold Flash on contact, Matte Tin on tail -C* = Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails			-K = (7,00mm) .275" DIA Polyimide Film Pick & Place Pad -TR = Tape and Reel (60 positions maximum)

Mates with:
BSE

LEAD STYLE	A
-01	(4,27) .168
-02	(7,21) .284

STACK HEIGHT

LEAD STYLE	MATED HEIGHT WITH BSE
-01	(5,00) .197
-02	(8,00) .315

Processing conditions will affect mated height.

APPLICATION SPECIFIC

- 30µ" (0,76µm) Gold
 - Edge Mount Capability
 - Friction Lock option
 - 11mm, 14mm, 16,10mm, 19,10mm, 22mm, 25mm and 30mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- Call Samtec.

*Note: -C Plating passes 10 year MFG testing
Note: Some lengths, styles and options are non-standard, non-returnable.

BSE	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
	-020, -040, -060, -080, -100, -120		-L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail -F = Gold Flash on contact, Matte Tin on tail -C* = Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails			-TR = Tape and Reel (80 positions maximum)

Mates with:
BTE

Due to technical progress, all designs, specifications and components are subject to change without notice.